L Number	Hits	Search Text	DB	Time stamp
-	65857	83/\$.ccls.	USPAT;	2004/06/08
			US-PGPUB; EPO; JPO;	16:02
			DERWENT;	
_	166767	29/\$.ccls.	IBM_TDB USPAT;	2004/04/16
			US-PGPUB;	10:18
			EPO; JPO; DERWENT;	
	F 002	205/2	IBM_TDB	2002/04/20
_	5993	225/\$.ccls.	USPAT; US-PGPUB;	2003/04/20 14:19
			EPO; JPO; DERWENT;	
			IBM_TDB	
-	9355	125/\$.ccls.	USPAT; US-PGPUB;	2003/04/20
			EPO; JPO;	14.15
			DERWENT; IBM TDB	
_	61690	451/\$.ccls.	USPAT;	2003/04/20
			US-PGPUB; EPO; JPO;	14:19
			DERWENT;	
_	150	tape near3 (bur or burr)	IBM_TDB USPAT;	2004/06/08
			US-PGPUB;	15:59
			EPO; JPO; DERWENT;	
	1211500		IBM_TDB	2004/06/00
_	1311500	semiconductor or wafer	USPAT; US-PGPUB;	2004/06/08 15:59
			EPO; JPO; DERWENT;	
	,		IBM_TDB	
-	17	(tape near3 (bur or burr)) and (semiconductor or wafer)	USPAT; US-PGPUB;	2003/04/20 14:22
		(Semiconductor or water)	EPO; JPO;	11.22
			DERWENT; IBM TDB	
-	5	' ' E - ' '	USPAT;	2003/04/20
		(semiconductor or wafer)) and (83/\$.ccls. or 29/\$.ccls. or 225/\$.ccls. or	US-PGPUB; EPO; JPO;	14:23
		125/\$.ccls. or 451/\$.ccls.)	DERWENT;	
_	1667037	cut or cutting	IBM_TDB USPAT;	2003/04/20
			US-PGPUB;	14:52
			EPO; JPO; DERWENT;	
	63	/tano noar3 (bur or burn)) and (out or	IBM_TDB USPAT;	2003/04/20
_	63	(tape near3 (bur or burr)) and (cut or cutting)	US-PGPUB;	14:24
			EPO; JPO; DERWENT;	
			IBM_TDB	
-	11	((tape near3 (bur or burr)) and (cut or cutting)) and (semiconductor or wafer)	USPAT; US-PGPUB;	2003/04/20 14:25
		The state of the s	EPO; JPO;	
			DERWENT; IBM TDB	
-	7		USPĀT;	2003/04/20
		cutting)) and (semiconductor or wafer)) not (((tape near3 (bur or burr)) and	US-PGPUB; EPO; JPO;	14:25
		(semiconductor or wafer)) and (83/\$.ccls. or 29/\$.ccls. or 225/\$.ccls. or	DERWENT;	
		125/\$.ccls. or 451/\$.ccls.))	IBM_TDB	

-	98065	156/\$.ccls.	USPAT;	2003/04/20
			US-PGPUB;	14:35
1			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	9	, ,	USPAT;	2003/04/20
		burr))	US-PGPUB;	14:36
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	0000 (04 (00
-	197	tape near4 (bur or burr)	USPAT;	2003/04/20
			US-PGPUB;	14:37
			EPO; JPO;	
			DERWENT;	
	19	/tame meand /hour on hours) \ and	IBM_TDB USPAT;	2003/04/20
-	19	(tape near4 (bur or burr)) and (semiconductor or wafer)	US-PGPUB;	14:40
		(Semiconductor of water)	EPO; JPO;	14.40
			DERWENT;	
			IBM TDB	
1_	1176677	sensor	USPAT;	2003/04/20
	11/00//	SCHOOL	US-PGPUB;	14:52
		•	EPO; JPO;	1
	1		DERWENT;	
			IBM TDB	
_	10	sensor and (tape near3 (bur or burr))	USPAT;	2003/04/20
	1		US-PGPUB;	14:47
	1		EPO; JPO;	1
			DERWENT;	
			IBM TDB	1
_	165735	83/\$.ccls. or 29/\$.ccls. or 225/\$.ccls.	USOCR	2003/04/20
		or 125/\$.ccls. or 451/\$.ccls. or		14:50
}		156/\$.ccls.		
-	11690	sensor	USOCR	2003/04/20
Ì	1			14:52
-	644428	cut or cutting	USOCR	2003/04/20
				14:52
-	26	tape near3 (bur or burr)	USOCR	2003/04/20
				14:53
-	27290	semiconductor or wafer	USOCR	2003/04/20
				14:52
-	31	tape near4 (bur or burr)	USOCR	2003/04/20
				14:53
-	1	(tape near4 (bur or burr)) and	USOCR	2003/04/20
1	_	(semiconductor or wafer)		14:53
-	36	tape near5 (bur or burr)	USOCR	2003/04/20
	_	A Company of the Comp	110005	14:53
_	1	(tape near5 (bur or burr)) and	USOCR	2003/04/20
	2451	(semiconductor or wafer)	HEOCE	14:54
-	3451	sensor and (cut or cutting)	USOCR	2003/04/20
	212	/congon and /gut an gutting!	HEOCE	14:54
-	313	(sensor and (cut or cutting)) and	USOCR	2003/04/20
_	0	(semiconductor or wafer) ((sensor and (cut or cutting)) and	USOCR	2003/04/20
~		(semiconductor or wafer)) and (tape near4	03000	14:54
		(bur or burr))		17.57
_	9	(83/\$.ccls. or 29/\$.ccls. or 225/\$.ccls.	USOCR	2003/04/20
		or 125/\$.ccls. or 451/\$.ccls. or	32001	14:54
		156/\$.ccls.) and (tape near3 (bur or		
		burr))		
-	7	("4865677" "4925515" "5069738"	USPAT	2003/04/21
		"5228944" "5310442" "5472554"		08:27
		"5688354").PN.		
-	0	6258198.URPN.	USPAT	2003/04/21
				08:28
-	77	tape near5 (bur or burr)	USPAT;	2003/04/21
	!		US-PGPUB;	08:35
			EPO; JPO;	
			DERWENT;	
	1		IBM TDB	Î

-	2	(tape near5 (bur or burr)) and sensor	USPAT; US-PGPUB; EPO; JPO;	2003/04/21 08:35
			DERWENT; IBM TDB	
-	4290	((83/13) or (83/23) or (83/27) or (83/28) or (83/34) or (83/36) or (83/61) or	USPAT; US-PGPUB;	2003/04/21 08:55
		(83/73) or (83/75) or (83/76.7) or (83/78) or (83/365) or (83/401) or	EPO; JPO; DERWENT;	
		(83/523) or (83/663) or (83/922) or (83/929.1)).CCLS.	IBM_TDB	
-	4682	((156/253) or (156/267) or (156/353) or (156/522) or (156/64) or (156/250)).CCLS.	USPAT; US-PGPUB;	2003/04/21 08:55
			EPO; JPO; DERWENT;	
_	5867	((451/41) or (451/63) or (451/28) or	IBM_TDB USPAT;	2003/04/21
		(451/6) or (451/285) or (451/287) or (451/288) or (451/413) or	US-PGPUB; EPO; JPO;	08:56
		(451/402)).CCLS.	DERWENT; IBM_TDB	:
-	0	(((83/13) or (83/23) or (83/27) or (83/28) or (83/34) or (83/36) or (83/61)	USPAT; US-PGPUB;	2003/04/21 08:56
	·	or (83/73) or (83/75) or (83/76.7) or (83/78) or (83/365) or (83/401) or	EPO; JPO; DERWENT;	
		(83/523) or (83/663) or (83/922) or (83/929.1)).CCLS.) and (((156/253) or	IBM_TDB	
		(156/267) or (156/353) or (156/522) or (156/64) or (156/250)).CCLS.) and		
		(((451/41) or (451/63) or (451/28) or (451/6) or (451/285) or (451/287) or		
		(451/288) or (451/413) or (451/402)).CCLS.)		0000/04/04
-	29	(((83/13) or (83/23) or (83/27) or (83/28) or (83/34) or (83/36) or (83/61)	USPAT; US-PGPUB;	2003/04/21 08:56
		or (83/73) or (83/75) or (83/76.7) or (83/78) or (83/365) or (83/401) or (83/523) or (83/663) or (83/922) or	EPO; JPO; DERWENT; IBM TDB	
		(83/929.1)).CCLS.) and (((156/253) or (156/267) or (156/353) or (156/522) or	15155	
_	654047	(156/64) or (156/250)).CCLS.) detect or detector	USPAT;	2003/04/21
			US-PGPUB; EPO; JPO;	09:36
			DERWENT; IBM_TDB	
-	77	tape near5 (bur or burr)	USPAT; US-PGPUB;	2003/04/21 09:36
			EPO; JPO; DERWENT;	
-	1	(detect or detector) and (tape near5 (bur	IBM_TDB USPAT;	2003/04/21
		or burr))	US-PGPUB; EPO; JPO;	09:36
			DERWENT; IBM_TDB	0000/01/01
_	77447	detect or detector	USOCR	2003/04/21
_	36	tape near5 (bur or burr)	USOCR	2003/04/21
	3	(detect or detector) and (tape near5 (bur or burr)) ("4865677").PN.	USOCR	2003/04/21 09:36
	2	(40000//).EN.	USPAT; US-PGPUB; EPO; JPO;	2003/11/02 13:51
			DERWENT; IBM TDB	
-	3	("4510009" "4680079" "4696712").PN.	USPAT	2003/11/02 13:52
-	8	4865677.URPN.	USPAT	2003/11/02 13:55
L	L	Landa and the second	<u> </u>	

	210549	tane	USPAT	2003/11/02
_	210549	tape		13:55
-	7	4865677.URPN. and tape	USPAT	2003/11/02 14:13
1_	2	("6116988").PN.	USPAT;	2003/11/02
		(0120300)	US-PGPUB;	14:14
			EPO; JPO;	
		·	DERWENT; IBM TDB	
-	210549	tape and tape	USPAT;	2003/11/02
			US-PGPUB;	14:14
·	ļ		EPO; JPO; DERWENT;	
			IBM_TDB	
-	1	tape and (("6116988").PN.)	USPAT;	2003/11/02
			US-PGPUB; EPO; JPO;	14:30
			DERWENT;	
			IBM_TDB	
-	2	("5422163").PN.	USPAT; US-PGPUB;	2003/11/02
			EPO; JPO;	11.30
		•	DERWENT;	
	,	tane and (/85/221/28) PM)	IBM_TDB	2002/11/02
-	1	tape and (("5422163").PN.)	USPAT; US-PGPUB;	2003/11/02
			EPO; JPO;	=
			DERWENT;	
_	1	(tape and (("5422163").PN.)) and cut	IBM_TDB USPAT;	2003/11/02
	1	(cape and ((5122105).IN.)) and out	US-PGPUB;	14:46
			EPO; JPO;	
			DERWENT; IBM TDB	
_	. 3	("3909915").PN.	USPAT;	2003/11/02
			US-PGPUB;	14:47
		,	EPO; JPO; DERWENT;	
			IBM TDB	
-	. 0	(("3909915").PN.) and tape and cut	USPAT;	2003/11/02
			US-PGPUB;	14:47
			EPO; JPO; DERWENT;	
			IBM_TDB	
-	1	(("3909915").PN.) and tape	USPAT; US-PGPUB;	2003/11/02
			EPO; JPO;	14:4/
			DERWENT;	
	_	/"E 6992E 4"\ DN	IBM_TDB	2002/11/02
-	2	("5688354").PN.	USPAT; US-PGPUB;	2003/11/02 14:47
			EPO; JPO;	
			DERWENT;	
_	1	(("5688354").PN.) and tape and cut	IBM_TDB USPAT;	2003/11/02
	_	, , , , , , , , , , , , , , , , , , ,	US-PGPUB;	14:48
			EPO; JPO;	
			DERWENT; IBM TDB	
-	0	((("5688354").PN.) and tape and cut) and	USPAT;	2003/11/02
		burr	US-PGPUB;	14:52
			EPO; JPO; DERWENT;	
			IBM TDB	•
-	6	(USPĀT;	2003/11/02
		("4680079")).PN.	US-PGPUB; EPO; JPO;	14:53
			DERWENT;	
			IBM_TDB	

		<u> </u>		
_	1670	tape and cut and burr	USPAT;	2003/11/02
			US-PGPUB;	14:53
	}		EPO; JPO;	
			DERWENT;	
	}		IBM_TDB	
_	0		USPAT;	2003/11/02
	1	("4680079")).PN.) and (tape and cut and	US-PGPUB;	14:53
	I	burr)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	172177	29/\$.ccls.	USPAT;	2004/04/16
ľ			US-PGPUB;	10:18
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	27332	tape near3 (remove or removing or cut or	USPAT;	2004/04/16
		cutting)	US-PGPUB;	10:19
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	348610	wafer	USPAT;	2004/04/16
			US-PGPUB;	10:19
			EPO; JPO;	
			DERWENT;]
			IBM_TDB	
-	3433833	sensor or detect or sensing or sensed or	USPAT;	2004/04/16
		detecting or detected	US-PGPUB;	10:19
		-	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	1364	(tape near3 (remove or removing or cut or	USPAT;	2004/04/16
		cutting)) and wafer	US-PGPUB;	10:20
		5	EPO; JPO;	1
			DERWENT;	1
			IBM TDB	
_	90	((tape near3 (remove or removing or cut	USPAT;	2004/04/16
		or cutting)) and wafer) and 29/\$.ccls.	US-PGPUB;	10:20
			EPO; JPO;	
			DERWENT;	1
			IBM TDB	1
-	22	(((tape near3 (remove or removing or cut	USPAT;	2004/06/08
		or cutting)) and wafer) and 29/\$.ccls.)	US-PGPUB;	16:04
		and (sensor or detect or sensing or	EPO; JPO;	
		sensed or detecting or detected)	DERWENT;	
		· · · · · · · · · · · · · · · · · · ·	IBM TDB	
-	2173	backgrinding or (back near2 grinding)	USPAT;	2004/04/16
			US-PGPUB;	10:22
			EPO; JPO;	
			DERWENT;	
			IBM TDB	[
-	6	(((tape near3 (remove or removing or cut	USPĀT;	2004/04/16
		or cutting)) and wafer) and 29/\$.ccls.)	US-PGPUB;	10:22
		and (backgrinding or (back near2	EPO; JPO;	
	1	grinding))	DERWENT;	
		[IBM TDB	
-	152025	438/\$.ccls.	USPAT;	2004/06/08
			US-PGPUB;	15:59
			EPO; JPO;	
			DERWENT;	
1			IBM TDB	
-	3710	438/\$.ccls.	USOCR	2004/06/08
i		,		16:03
-	162	tape near3 (bur or burr)	USPAT;	2004/06/08
			US-PGPUB;	16:03
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	26	tape near3 (bur or burr)	USOCR	2004/06/08
				16:03
		· · · · · · · · · · · · · · · · · · ·	L	

_	1498239	semiconductor or wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/08
-	27277	semiconductor or wafer	USOCR	2004/06/08
-	0	sensor or sensed or sensing or detect or detected or detecting	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	16:02 2004/06/08 16:01
-	5166058	sensor or sensing or sensed or detect or detected or detecting or determine or determined or determining or encoder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/08 16:02
-	27277	semiconductor or wafer	USOCR	2004/06/08
-	1498239	semiconductor or wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/08
-	26	tape near3 (bur or burr)	USOCR	2004/06/08 17:28
-	162	tape near3 (bur or burr)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/08 16:07
-	3710	438/\$.ccls.	USOCR	2004/06/08 16:03
-	152025	438/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/08 16:03
-	1383	((tape near3 (remove or removing or cut or cutting)) and wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/08 16:08
_	43	((tape near3 (remove or removing or cut or cutting)) and wafer)	USOCR	2004/06/08
_	588449	sensor or sensing or sensed or detect or detected or detecting or determine or determined or determining or encoder	USOCR	2004/06/08
-	2	(tape near3 (bur or burr)) and 438/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/08
-	0	(tape near3 (bur or burr)) and 438/\$.ccls.	usocr	2004/06/08 16:08
-	106	438/\$.ccls. and tape	USOCR	2004/06/08 16:08
_	689	(tape near4 (remove or removing or cut or cutting)) and (tape and 438/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/08 16:10
-	9	(tape near4 (remove or removing or cut or cutting)) and (438/\$.ccls. and tape)	USOCR	2004/06/08 16:10
-	21	438/\$.ccls. and (bur or burr)	USOCR	2004/06/08 16:33
-	775	438/\$.ccls. and (bur or burr)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/08 16:35

-	26	(438/\$.ccls. and (bur or burr)) and	USPAT;	2004/06/08
		((tape near4 (remove or removing or cut	US-PGPUB;	16:35
		or cutting)) and (tape and 438/\$.ccls.))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	i
-	14	tape near2 (bur or burr)	USOCR	2004/06/08
				17:29
-	109	tape near2 (bur or burr)	USPAT;	2004/06/08
			US-PGPUB;	17:29
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	